ASSOCIATION CONNECTING LECTRONICS INDUSTRIES® INCLUSTRIES®	C. Bannockł	ourn. Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declara he declaration	ion of the s encompasse	ubstances es all lowe	within the r level mat	manufacture erials for wh	er listed ite nich the ma	m. Note: nufacture	if the item is an as er has engineering	sembly with lower responsibility.
	I.1IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175xForm Dist				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Material					als and Mfg Information				
Supplier Information														
Company name* Co			Company unique ID			Unique ID Authority					Response Date*			
onsemi											2025-06-07			
Contact Name Title - Contact			ct			Phone - Contact*				Email - Contact*				
Product-Env-Stewards Product Er			ct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Rep			Representative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product Env			Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item	Number Mfr Item Name				Effective Dat	e Version]	Manufacturing Site		W	eight*	UOM	Unit Type
	MSRD6	20CTT4RG	6 A 200 V ULTRASOFT RECT			2025-06-07			VN5		35	53.13	mg	Each
Manufacturing Proccess Informat	ion													
Terminal Plating / Grid Array Ma	minal Plating / Grid Array Material Terminal Base		Alloy	J-STD-020 MSL Rating		Peak Pro	Peak Process Body Temperature		re Max Ti	me at Peak 🕻	k Temperature Number of Reflow Cycles		cles	
Matte Tin (Sn) - annealed CU Alloy			1		260		С	30		second	s 3			
Comments														
evel 1 - maximum time at peak temperatu	re during so	Idering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declar	ation			Declaration Type *	Detailed
Directive 2015/863/EU amending Rol Directive 2011/65/EU	(Pb), Mercury (Hg), Hexav		ninated Biphenyls (PBB), Polybror	dmium and quantity limit of 0.1% by mass (100 ninated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polyb contains a RoHS restricted substance i encompass all such components.Suppl as of the date that Supplier completes Company acknowledges that Supplier independently verified information pro- certification in this paragraph.If the Co	rominated biphenyls and/or polybror nexcess of an applicable quantity lim ier certifies that it gathered the inforr this form.Supplier acknowledges that may have relied on informationprovi ovided by others, Supplier agrees that ompany and the Supplier enter into a clusivesource of the Supplier's liabili	ninated diphenyl ethers (each a "R it, please indicate below which, if nation it provides in this form usin Company will rely on this certifud ded by others in completing this f , at a minimum, itssuppliers have written agreement with respect to ty and the Company's remedies for	toHS restricted substance") in exce any, RoHS exemption you believe ag appropriate methods to ensure it cation in determining the complian orm, and that Supplier may not hav provided certifications regarding th the identified part, the terms and co or issues that arise regarding inform	ropean Union member states) of the part identifies so of the applicable quantity limit identified about may apply. If the part is an assembly with lows a accuracy and that such information is true and ce of its products with European Union member re independently verified such information. How heir contributions to the part, and those certifica motions of that agreement, including any warra nation the Supplier provides in this form. In the	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of
RoHS Declaration * 4	- Item(s) does not contain RoHS restr	icted substances per the definition	above except for selected exempti	ons Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high meltin Exemption: 7c-I Electrical and elect	g temperature type solders (i.e. lead ronic components containing lead i	l based solder alloys containing n a glass or ceramic other than	85% by weight or more lead). dielectric ceramic in capacitors, o	e.g. piezoelectronic devices, or in a glass or ce	eramic matrix compound.
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the rec Requester) and click on Submit For			Supplier Acceptance drop-down	. This will display the signature area. Digital	ly sign the declaration (if required by the
Supplier Digital Signature	Rastislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.2	mg	Supplier	Silicon (Si)	7440-21-3		0.198	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.002	mg
Die Attach	1.4	mg	А	Lead (Pb)	7439-92-1	7a	1.33	mg
			Supplier	Tin (Sn)	7440-31-5		0.07	mg
Lead Frame	214.64	mg	В	Nickel (Ni)	7440-02-0		0.4293	mg
			Supplier	Copper (Cu)	7440-50-8		214.2107	mg
Mold Compound	129.65	mg		Epoxy resin	proprietary data		1.9447	mg
			Supplier	Hardener	Proprietary Data		6.4825	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		9.7238	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2593	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		111.2397	mg
Plating	3.73	mg	Supplier	Tin (Sn)	7440-31-5		3.73	mg
Wire Bond - Al	3.51	mg	Supplier	Aluminum (Al)	7429-90-5		3.51	mg